

PRODUCT/PROCESS CHANGE NOTICE (PCN)						
PCN Number: 21001 Means of Distinguishing Date Issued: 8/13/2021 Changed Devices:						
Product(s) A		Product Mark: Back Mark				
	SP3222EBCA-L/TR	SP3222EBEA-L/TR	SP3222EBEY-L/TR		Date Code	
	SP3222ECA-L/TR	SP3222ECY-L/TR	SP3222EEA-L/TR		Other: Lot number	
	SP3222EEY-L	SP3222EEY-L/TR	SP3222EUCY-L/TR			
	SP3222EUEY-L/TR	SP3232EBCA-L/TR	SP3232EBCN-L			
	SP3232EBCN-L/TR	SP3232EBCY-L/TR	SP3232EBEN-L/TR			
	SP3232EBER-L/TR	SP3232EBEY-L/TR	SP3232ECA-L			
	SP3232ECA-L/TR	SP3232ECN-L	SP3232ECN-L/TR			
	SP3232ECY-L	SP3232ECY-L/TR	SP3232EEA-L			
	SP3232EEA-L/TR	SP3232EEN-L	SP3232EEN-L/TR			
	SP3232EEY-L	SP3232EEY-L/TR	SP3232EHCY-L/TR			
	SP3232EHEY-L/TR	SP3232EUCN-L	SP3232EUCN-L/TR			
	SP3232EUCY-L/TR	SP3232EUEA-L/TR	SP3232EUEY-L/TR			
Manufacturing Location Affected: Refer to Description and Purpose of Change below						
Date Effective (90 day window): August 13, 2021						
Date Issued +90 days: November 13, 2021						
Contact: Your local MaxLinear Marketing Representative or contact our Customer Support team by creating a Support Ticket at http://www.maxlinear.com/support/createcase					Attachment: Yes No	
Phone: 1-760-692-0711					Samples:	
					Request from MaxLinear Marketing Representatives	
Description and Purpose of Change: MaxLinear has qualified Key Foundry wafer foundry in order to increase production capacity and to facilitate long term support of the product line. The wafer process is 0.18um BCD. There is no change to form, fit, function and the products meet existing datasheet specifications. In addition to the currently qualified ANST site, Greatek is added as an alternate site for package, assembly, and test. There are no changes in device reliability. Note: Users who rely on DC, diode characteristics during ICT testing should take caution certain I/O characteristics may appear changed due to the proprietary I/O structures employed by Key Foundry. These DC / diode characteristic differences are not guaranteed nor required to ensure full design functionality per datasheet. Adjustments at ICT testing may be required to prevent false failures.					Die Technology Wafer Fabrication Assembly Process Equipment Material Testing Product Design Manufacturing Site Data Sheet Yield Enhancement Software Other:	
Reliability/Qualification Summary: Reliability reports available upon request						



PCN-21001 SP32XXXX-L/TR Process Change Notification

Customer Acknowledgement of Receipt within 30 days acceptance of change.	s of issue. Lack of acknowledgement within 30 days constitutes
Please fax or email this form to the contact above after	r completing the following information:
Customer:	
Name:	
Title:	
Date:	
E-Mail:	
Phone:	
Fax:	
Approval for shipments prior to effective date	
Customer Comments (Optional):	